

In the Specification

Please change the title to "Semiconductor Component Having Redistribution Conductors And Bumped Contacts On Selected Portions Thereof".

On page 2, line 1, add the following:

-- Cross Reference To Related Applications

This application is a continuation of Serial No. 10/659,828, filed 09/11/03, which is a continuation of Serial No. 09/835,200, filed 04/13/2001, Patent No. 6,620,633, which is a division of Serial No. 09/473,232, filed 12/24/1999, Patent No. 6,380,555 B1. --

In the paragraph on page 20, lines 6-12, please make the following changes.

-- The test carrier 100 also includes an alignment member 108 adapted to align the components ~~40~~ 50, to the interconnect 72D such that the interconnect contacts 42D electrically engage the test contacts 60 (Figure 6C). The alignment member 108 includes openings 110 configured to contact the peripheral edges of the components 50 to guide the components 50 onto the interconnect 72D.--